

### LOW EMI CLOCK GENERATOR

ICS4231-03

## **Description**

The ICS4231-03 generates a low EMI output clock from a clock or crystal input. The device uses ICS' proprietary mix of analog and digital Phase Locked Loop (PLL) technology to spread the frequency spectrum of the output, thereby reducing the frequency amplitude peaks by several dB.

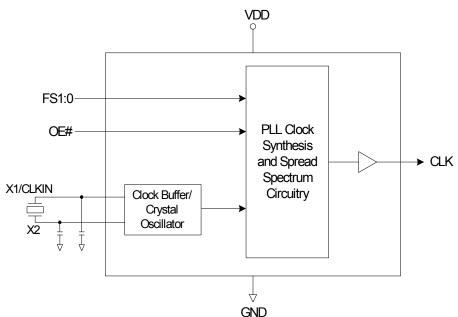
The ICS4231-03 offers four different center and down spread selections. Refer to the MK1714-01/02 for the widest selection of input frequencies and multipliers.

ICS offers a complete line of EMI reducing clock generators. Consult us when you need to remove crystals and oscillators from your board.

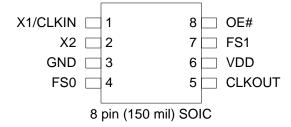
#### **Features**

- Pin and function compatible to Cypress W42C31-03
- Packaged in 8-pin SOIC (Pb free available)
- Provides a spread spectrum output clock
- Accepts a clock or crystal input and provides same frequency dithered output
- Input clock frequency of 10 to 33 MHz
- Peak reduction by 8dB 14dB typical on 3rd 19th odd harmonics
- Spread percentage selections of ±1.875%, ±1.0%, and -2.0%
- Operating voltage of 5V
- Advanced, low-power CMOS process

## **Block Diagram**



## **Pin Assignment**



# **Output Enable Function Table**

OE# (Pin 8)	Output Status
0	Running
1	Tri-state

0 = connect to GND

1 = connect directly to VDD

Note: OE# pin has an internal pull-down resistor

## **Frequency Range and Spread Table**

FS1 (Pin 7)	FS0 (Pin 4)	Clock Input Frequency (MHz)	Crystal Input Frequency (MHz)	Spread Amount
0	0	10-20	10-20	±1.875%
0	1	10-20	10-20	±1.0%
1	0	20-33	20-25	±1.875%
1	1	20-33	20-25	-2.0%

Note: FS1:0 have internal pull-up resistors

## **Pin Descriptions**

Pin Number	Pin Name	Pin Type	Pin Description
1	X1/CLKIN	Input	Crystal or Clock Input.
2	X2	Output	Crystal output. Float for a clock input.
3	GND	Power	Connect to ground.
4	FS0	Input	Select pin for input frequency and spread amount. See table above. Internal pull up resistor.
5	CLKOUT	Output	Spread spectrum clock output per table above.
6	VDD	Power	Connect to 5V.
7	FS1	Input	Select pin for input frequency and spread amount. See table above. Internal pull up resistor.
8	OE#	Input	Output Enable. Active Low. See table above. Internal pull-down resistor.

### **External Components**

The ICS4231-03 requires a minimum number of external components for proper operation.

#### **Decoupling Capacitor**

A decoupling capacitor of 0.01µF must be connected between VDD and GND on pins 6 and 3, as close to these pins as possible. For optimum device performance, the decoupling capacitor should be mounted on the component side of the PCB. Avoid the use of vias in the decoupling circuit.

#### **Series Termination Resistor**

When the PCB trace between the clock output and the load is over 1 inch, series termination should be used. To series terminate a  $50\Omega$  trace (a commonly used trace impedance) place a  $33\Omega$  resistor in series with the clock line, as close to the clock output pin as possible. The nominal impedance of the clock output is  $20\Omega$ 

value of these capacitors is given by the following equation:

### PCB Layout Recommendations

For optimum device performance and lowest output phase noise, the following guidelines should be observed.

- 1) The 0.01µF decoupling capacitor should be mounted on the component side of the board as close to the VDD pin as possible. No vias should be used between the decoupling capacitor and VDD pin. The PCB trace to VDD pin should be kept as short as possible, as should the PCB trace to the ground via.
- 2) To minimize EMI the  $33\Omega$  series termination resistor. if needed, should be placed close to the clock output.
- 3) An optimum layout is one with all components on the same side of the board, minimizing vias through other signal layers. Other signal traces should be routed away from the ICS4231-03. This includes signal traces just underneath the device, or on layers adjacent to the ground plane layer used by the device.

### **Absolute Maximum Ratings**

Stresses above the ratings listed below can cause permanent damage to the ICS4231-03. These ratings, which are standard values for ICS commercially rated parts, are stress ratings only. Functional operation of the device at these or any other conditions above those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods can affect product reliability. Electrical parameters are guaranteed only over the recommended operating temperature range.

Item	Rating
Supply Voltage, VDD	7V
All Inputs and Outputs	-0.5V to VDD+0.5V
Ambient Operating Temperature	0 to +70° C
Storage Temperature	-65 to +150° C
Junction Temperature	125° C
Soldering Temperature	260° C

### **DC Electrical Characteristics**

Unless stated otherwise, VDD = 5V, ±10%, Ambient Temperature 0 to +70°C

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Units
Operating Voltage	VDD		4.5	5	5.5	V
Supply Current	IDD	No load, at 3.3V		18	32	mA
Input High Voltage	V <sub>IH</sub>		0.7VDD			V
Input Low Voltage	V <sub>IL</sub>				0.15VDD	V
Output High Voltage	V <sub>OH</sub>	I <sub>OH</sub> = -24mA	2.5			V
Output Low Voltage	V <sub>OL</sub>	I <sub>OL</sub> = 24mA			0.4	V
Input Capacitance	C <sub>IN</sub>	All pins except X1, X2		5	7	pF
Load Capacitance		X1, X2, as seen by the xtal, Note 1		17		pF
Output Impedance	Rout			20		Ω
Input Pull-Up Resistor				500		ΚΩ
Power-Up Time		First locked clock cycle after Power Good			5	ms

Note 1: Pins X1 and X2 each have 34 pF capacitance. When used with a crystal, the total combined capacitance as seen by the crystal is 17 pF. If driving X1 with a clock input, the load capacitance will be 34 pF.

### **AC Electrical Characteristics**

Unless stated otherwise, VDD = 5V±10%, Ambient Temperature 0 to +70° C, C<sub>L</sub>=15pf

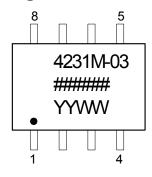
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Units
Input Frequency		Input Clock	10		33	MHz
Output Frequency			10		33	MHz
Input Clock Duty Cycle		Time above VDD/2	40		60	%
Output Clock Duty Cycle		Note 1	45	50	55	%
Output Rise Time	t <sub>OR</sub>	0.8 to 2.4V, note 1		2	5	ns
Output Fall Time	t <sub>OF</sub>	2.4 to 0.8V, note 1		2	5	ns
Jitter		cycle-to-cycle			300	ps
Harmonic Reduction			8			dB

Note 1: Measured with 15pF load

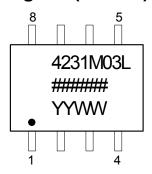
### **Thermal Characteristics**

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Units
Thermal Resistance Junction to	$\theta_{JA}$	Still air		150		° C/W
Ambient	$\theta_{JA}$	1 m/s air flow		140		° C/W
	$\theta_{JA}$	3 m/s air flow		120		° C/W
Thermal Resistance Junction to Case	$\theta_{JC}$			40		° C/W

## **Marking Diagram**



## Marking Diagram (Pb free)

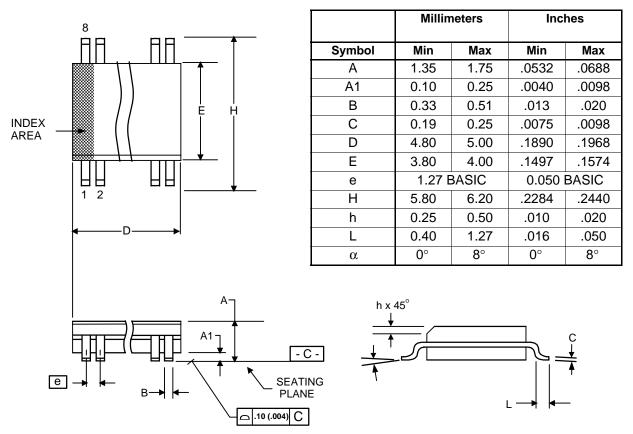


#### Notes:

- 1. ##### is the lot number.
- 2. YYWW is the last two digits of the year and week that the part was assembled.
- 3. "L" denotes Pb (lead) free package.
- 4. Bottom marking: country of origin.

### Package Outline and Package Dimensions (8 pin SOIC, 150 Mil. Body)

Package dimensions are kept current with JEDEC Publication No. 95



## **Ordering Information**

Part / Order Number	Marking	Shipping packaging	Package	Temperature
4231M-03		Tubes	8-pin SOIC	0 to +70° C
4231M-03T	see page 5	Tape and Reel	8-pin SOIC	0 to +70° C
4231M-03LF		Tubes	8-pin SOIC	0 to +70° C
4231M-03LFT		Tape and Reel	8-pin SOIC	0 to +70° C

<sup>&</sup>quot;LF" denotes Pb free packaging.

While the information presented herein has been checked for both accuracy and reliability, Integrated Circuit Systems (ICS) assumes no responsibility for either its use or for the infringement of any patents or other rights of third parties, which would result from its use. No other circuits, patents, or licenses are implied. This product is intended for use in normal commercial applications. Any other applications such as those requiring extended temperature range, high reliability, or other extraordinary environmental requirements are not recommended without additional processing by ICS. ICS reserves the right to change any circuitry or specifications without notice. ICS does not authorize or warrant any ICS product for use in life support devices or critical medical instruments.

## Innovate with IDT and accelerate your future networks. Contact:

www.IDT.com

### For Sales

800-345-7015 408-284-8200 Fax: 408-284-2775

#### For Tech Support

oduct line email>

#### **Corporate Headquarters**

Integrated Device Technology, Inc. 6024 Silver Creek Valley Road San Jose, CA 95138 United States 800 345 7015 +408 284 8200 (outside U.S.)

#### **Asia Pacific and Japan**

Integrated Device Technology Singapore (1997) Pte. Ltd. Reg. No. 199707558G 435 Orchard Road #20-03 Wisma Atria Singapore 238877 +65 6 887 5505

#### **Europe**

IDT Europe, Limited Prime House Barnett Wood Lane Leatherhead, Surrey United Kingdom KT22 7DE +44 1372 363 339

